

## SLOVENSKI STANDARD SIST EN IEC 61000-4-20:2022

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#### Elektromagnetna združljivost (EMC) - 4-20. del: Preskusne in merilne tehnike -Preskušanje oddajanja in odpornosti v prečnih elektromagnetnih (TEM) valovodih

Electromagnetic compatibility (EMC) - Part 4-20: Testing and measurement techniques -Emission and immunity testing in transverse electromagnetic (TEM) waveguides

Elektromagnetische Verträglichkeit (EMV) - Teil 4-20: Prüf- und Messverfahren -Messung der Störaussendung und Prüfung der Störfestigkeit in transversalelektromagnetischen (TEM-)Wellenleitern

EN IEC 61000-4-20:2022

Compatibilité électromagnétique (CEM) - Partie 4-20: Techniques d'essai et de mesure - Essais d'émission et d'immunité dans les guides d'onde TEM

Ta slovenski standard je istoveten z: EN IEC 61000-4-20:2022

#### ICS:

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Emission Immunity

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# EUROPEAN STANDARD NORME EUROPÉENNE EUROPÄISCHE NORM

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Supersedes EN 61000-4-20:2010 and all of its amendments and corrigenda (if any)

**English Version** 

### Electromagnetic compatibility (EMC) - Part 4-20: Testing and measurement techniques - Emission and immunity testing in transverse electromagnetic (TEM) waveguides (IEC 61000-4-20:2022)

Compatibilité électromagnétique (CEM) - Partie 4-20: Techniques d'essai et de mesure - Essais d'émission et d'immunité dans les guides d'onde TEM (IEC 61000-4-20:2022) Elektromagnetische Verträglichkeit (EMV) - Teil 4-20: Prüfund Messverfahren - Messung der Störaussendung und Prüfung der Störfestigkeit in transversalelektromagnetischen (TEM-)Wellenleitern (IEC 61000-4-20:2022)

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#### 05c1036930/sist-en-iec-61000-4-20-202

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#### EN IEC 61000-4-20:2022 (E)

#### European foreword

The text of document 77B/853/FDIS, future edition 3 of IEC 61000-4-20, prepared by SC 77B "High frequency phenomena" of IEC/TC 77 "Electromagnetic compatibility" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61000-4-20:2022.

The following dates are fixed:

- latest date by which the document has to be implemented at national (dop) 2022-12-25 level by publication of an identical national standard or by endorsement
- latest date by which the national standards conflicting with the (dow) 2025-03-25 document have to be withdrawn

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### Endorsement notice

The text of the International Standard IEC 61000-4-20:2022 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

- IEC 60068-1 NOTE Harmonized as EN 60068-1
- IEC 60118-13 NOTE Harmonized as EN IEC 60118-13
- IEC 61967-2 NOTE Harmonized as EN 61967-2
- IEC 62132-2 NOTE Harmonized as EN 62132-2
- CISPR 25 NOTE Harmonized as EN IEC 55025
- CISPR 14 (series) NOTE Harmonized as EN IEC 55014-2 (series)
- CISPR 16-4-2 NOTE Harmonized as EN 55016-4-2
- IEC 61000-2-9 NOTE Harmonized as EN 61000-2-9
- IEC 61000-4-3 NOTE Harmonized as EN IEC 61000-4-3

CISPR 16-2-3:2016 NOTE Harmonized as EN 55016-2-3:2017 (not modified)

- CISPR 32 NOTE Harmonized as EN 55032
- CISPR 20:2006 NOTE Harmonized as EN 55020:2007 (not modified) +A11:2011

# **Annex ZA** (normative)

# Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: <u>www.cenelec.eu</u>.

Publication	Year	Title	<u>EN/HD</u>	<u>Year</u>
IEC 60050-161	-	International Electrotechnical Vocabulary (IEV) - Part 161: Electromagnetic compatibility	-	-
CISPR 16-1-1	iTeh	Specification for radio disturbance and immunity measuring apparatus and methods - Part 1-1: Radio disturbance and immunity measuring apparatus - Measuring apparatus	EN IEC 55016-1-1	-
CISPR 16-1-4 http:	s://standards a	Specification for radio disturbance and immunity measuring apparatus and methods - Part 1-4: Radio disturbance and immunity measuring apparatus - Antennas and test sites for radiated disturbance measurements	EN IEC 55016-1-4 -726f-43fd-89c2- 22	-

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#### CONTENTS

F	OREWC	RD	7
IN	TRODU	JCTION	9
1	Scop	e	10
2	Norm	native references	11
3	Term	is, definitions and abbreviated terms	11
	3.1	Terms and definitions	11
	3.2	Abbreviated terms	14
4	Gene	eral	15
5	TEM	waveguide requirements	15
	5.1	General	15
	5.2	General requirements for the use of TEM waveguides	16
	5.2.1	Test volume and maximum EUT size	16
	5.2.2	Validation of usable test volume	16
	5.3	Special requirements and recommendations for certain types of TEM waveguides	23
	5.3.1	Set-up of open TEM waveguides	23
	5.3.2	Alternative TEM mode verification for a two-port TEM waveguide	23
	5.3.3	TEM mode generation for a four-port TEM waveguide	23
	5.4	Figures for Clause 5	24
6	Over	view of EUT types	26
	6.1	General	26
	6.2	Small EUT	26
	6.3	Large EUT	26
7	Labo	ratory test conditions	26
	7.1	General	26
	7.2	Climatic conditions	26
	7.3	Electromagnetic conditions	26
8	Eval	uation and reporting of test results	27
A	nnex A	(normative) Emission measurements in TEM waveguides	28
	A.1	Overview	28
	A.2	Test equipment	28
	A.3	Correlating TEM waveguide voltages to electric field strength data	28
	A.3.1	General	28
	A.3.2	Correlation algorithms	29
	A.4	Emission measurement correction factors	33
	A.4.	Arrangement of amoli EUTo	33
	A.4.2	Calculation of the small EUT correction factor	34
	Δ 5	Emission measurement procedures in TEM waveguides	34
		FIIT types	37
	A 5 2	P FUT arrangement	
	A.6	Test report	
	A.7	Figures for Annex A	
A	nnex B	(normative) Immunity testing in TEM waveguides	44
	B.1	Overview	44
	B.2	Test equipment	44

D.Z. I	General	44
B.2.2	2 Description of the test facility	44
B.3	Field uniformity area calibration	45
B.4	Test levels	45
B.5	Test set-up	45
B.5.1	Arrangement of table-top equipment	45
B.5.2	2 Arrangement of floor-standing equipment	46
B.5.3	Arrangement of wiring	46
B.6	Test procedures	46
B.7	Test results and test report	46
B.8	Figures for Annex B	47
Annex C (	(normative) HEMP transient testing in TEM waveguides	49
C.1	Overview	49
C.2	Immunity tests	
C.2.1	l General	49
C.2.2	2 Radiated test facilities	
C.2.3	B Frequency domain spectrum requirements	
C 3	Test equipment	51
C.4	Test set-up	
C 5		52
C 5 1	General A DA C P C D	52
C 5 2	2 Severity level and test exposures	53
C 5 3	Test procedure Canciards. Iten. al	53
C 5 4	1 Test execution	54
C.5.5	5 Execution of the radiated immunity test	
C.6	Figure for Annex C:h.ai/catalog/standards/sist/37eddb27.726f-43fd-89c2-	
C.6 Annex D (	Figure for Annex C	55
C.6 Annex D (	Figure for Annex C.h.a./catalog/standards/sist/37eddb27.726f.43fd.89c2 (informative) TEM waveguide characterization	55
C.6 Annex D ( D.1 D 2	Figure for Annex C	55 56 56
C.6 Annex D ( D.1 D.2 D 3	Figure for Annex C	55 56 56 56 56
C.6 Annex D ( D.1 D.2 D.3	Figure for Annex C	55 56 56 56 56 57
C.6 Annex D ( D.1 D.2 D.3 D.3.1	Figure for Annex C. (informative) TEM waveguide characterization Overview Distinction between wave impedance and characteristic impedance TEM wave General	54 55 56 56 56 57 57
C.6 Annex D ( D.1 D.2 D.3 D.3.1 D.3.2 D.3.2	Figure for Annex C	54 55 56 56 57 57 57 57
C.6 Annex D ( D.1 D.2 D.3 D.3.1 D.3.2 D.3.3	Figure for Annex C. (informative) TEM waveguide characterization	
C.6 Annex D ( D.1 D.2 D.3 D.3.1 D.3.2 D.3.3 D.4	Figure for Annex C.         (informative) TEM waveguide characterization         Overview.         Distinction between wave impedance and characteristic impedance.         TEM wave         1 General         2 Free-space TEM mode         3 Waveguides.         Wave propagation	54 55 56 56 57 57 57 57 57 57
C.6 Annex D ( D.1 D.2 D.3 D.3.1 D.3.2 D.3.3 D.4 D.4.1 D.4 2	Figure for Annex C. (informative) TEM waveguide characterization Overview. Distinction between wave impedance and characteristic impedance. TEM wave. General Free-space TEM mode Waveguides. Wave propagation General	
C.6 Annex D ( D.1 D.2 D.3 D.3.1 D.3.2 D.3.3 D.4 D.4.1 D.4.2 D.4.3	Figure for Annex C.         (informative) TEM waveguide characterization         Overview.         Distinction between wave impedance and characteristic impedance.         TEM wave.         I General         2 Free-space TEM mode         3 Waveguides.         Wave propagation         1 General         2 Spherical propagation         3 Plane wave propagation in free space	54 55 56 56 57 57 57 57 57 58 58 58 58
C.6 Annex D ( D.1 D.2 D.3 D.3.1 D.3.2 D.3.3 D.4 D.4.1 D.4.2 D.4.3 D.4 4	Figure for Annex C.         (informative) TEM waveguide characterization         Overview.         Distinction between wave impedance and characteristic impedance.         TEM wave.         1 General         2 Free-space TEM mode         3 Waveguides.         Wave propagation         1 General         2 Spherical propagation         3 Plane wave propagation in free space	
C.6 Annex D ( D.1 D.2 D.3 D.3.1 D.3.2 D.3.3 D.4 D.4.1 D.4.2 D.4.3 D.4.4 D.4.4	Figure for Annex C.         (informative) TEM waveguide characterization         Overview.         Distinction between wave impedance and characteristic impedance.         TEM wave.         General         Pree-space TEM mode         Waveguides         Wave propagation         General         Spherical propagation         Plane wave propagation         Velocity of propagation         Polarization	54 55 56 56 57 57 57 57 57 58 58 58 58 58 58 58
C.6 Annex D ( D.1 D.2 D.3 D.3.1 D.3.2 D.3.3 D.4 D.4.1 D.4.2 D.4.3 D.4.3 D.4.4 D.5 D.6	Figure for Annex C Figure for Annex C (informative) TEM waveguide characterization 0.4.20.2022 Overview Distinction between wave impedance and characteristic impedance TEM wave General Free-space TEM mode Wave propagation General Spherical propagation Plane wave propagation Polarization Types of TEM waveguides	
C.6 Annex D ( D.1 D.2 D.3 D.3.1 D.3.2 D.3.3 D.4 D.4.1 D.4.2 D.4.3 D.4.4 D.5 D.6 D.6 1	Figure for Annex C.         Figure for Annex C.         (informative) TEM waveguide characterization         Overview.         Distinction between wave impedance and characteristic impedance.         TEM wave.         General         Pree-space TEM mode         Wave propagation         General         Spherical propagation         Plane wave propagation         Polarization         Polarization         Types of TEM waveguides	
C.6 Annex D ( D.1 D.2 D.3 D.3.1 D.3.2 D.3.3 D.4 D.4.1 D.4.2 D.4.3 D.4.4 D.5 D.6 D.6 D.6.1 D.6 2	Figure for Annex C	
C.6 Annex D ( D.1 D.2 D.3 D.3.1 D.3.2 D.3.3 D.4 D.4.1 D.4.2 D.4.3 D.4.4 D.5 D.6 D.6.1 D.6.1 D.6.2 D.6 3	Figure for Annex C	
C.6 Annex D ( D.1 D.2 D.3 D.3.1 D.3.2 D.3.3 D.4 D.4.1 D.4.2 D.4.3 D.4.4 D.5 D.6 D.6.1 D.6.2 D.6.3	Figure for Annex C.         (informative) TEM waveguide characterization         Overview.         Distinction between wave impedance and characteristic impedance.         TEM wave.         1       General         2       Free-space TEM mode         3       Waveguides.         Wave propagation       General         2       Spherical propagation         3       Plane wave propagation in free space         4       Velocity of propagation         7       Types of TEM waveguides (striplines, etc.)         3       Closed TEM waveguides (TEM cells)	
C.6 Annex D ( D.1 D.2 D.3 D.3.1 D.3.2 D.3.3 D.4 D.4.1 D.4.2 D.4.3 D.4.3 D.4.4 D.5 D.6 D.6.1 D.6.2 D.6.3 D.7 D.8	Figure for Annex C. hateral and and event and a definite and the second	
C.6 Annex D ( D.1 D.2 D.3 D.3.1 D.3.2 D.3.3 D.4 D.4.1 D.4.2 D.4.3 D.4.4 D.5 D.6 D.6.1 D.6.2 D.6.3 D.7 D.8 Annex E (	Figure for Annex C.h. at an analysis of the field of	
C.6 Annex D ( D.1 D.2 D.3 D.3.1 D.3.2 D.3.3 D.4 D.4.1 D.4.2 D.4.3 D.4.4 D.5 D.6 D.6.1 D.6.2 D.6.3 D.7 D.8 Annex E (	Figure for Annex C. h. d. entropy and the state of t	
C.6 Annex D ( D.1 D.2 D.3 D.3.1 D.3.2 D.3.3 D.4 D.4.1 D.4.2 D.4.3 D.4.4 D.5 D.6 D.6.1 D.6.2 D.6.3 D.7 D.8 Annex E ( E.1	Figure for Annex C. Indicated and evaluated and evalaxis and evaluated and evalated and evaluated	55 56 56 56 57 57 57 57 57 57 57 57 58 58 58 58 58 58 58 58 58 58 58 58 58
C.6 Annex D ( D.1 D.2 D.3 D.3.1 D.3.2 D.3.3 D.4 D.4.1 D.4.2 D.4.3 D.4.4 D.5 D.6 D.6.1 D.6.2 D.6.3 D.7 D.8 Annex E ( E.1 E.2	Figure for Annex C.h.alternion/antickie/Conduct 20.0002         (informative) TEM waveguide characterization 10.4.20.2002         Overview	

E.2.2	Calibration frequency range	69
E.2.3	Calibration volume	70
E.2.4	Probe dimensions	70
E.2.5	Perturbations of TEM waveguide fields due to the probe	70
E.2.6	Frequency steps	71
E.2.7	Field strength	71
E.3	Requirements for calibration instrumentation	71
E.3.1	Specifications of TEM waveguide	71
E.3.2	Harmonics and spurious signals	72
E.3.3	Probe fixture	72
E.3.4	Measuring net power to a transmitting device using directional couplers	72
E.4	E-field probe calibration	73
E.4.1	Calibration methods	73
E.4.2	Calibration procedure using a two-port TEM waveguide	73
E.4.3	Calibration procedure using one-port TEM waveguide	74
E.5	Figures for Annex E	77
Annex F (	informative) Instrumentation uncertainty of emission measurement results	79
F.1	Radiated disturbance measurements using a TEM waveguide	
F.1.1	Measurand for radiated disturbance measurements using a TEM	
	waveguide	79
F.1.2	Symbols of input quantities common to all disturbance measurements	79
F.1.3	Symbols of input quantities specific to TEM waveguide measurements	79
F.2	Input guantities to be considered for radiated disturbance measurements	
	using a TEM waveguide	79
F.3	Uncertainty budget and rationale for the input quantities for radiated	00
F 0 4	disturbance measurements using a TEM waveguide	80
F.3.1	waveguide	80
F.3.2	Rationale for the estimates of input quantities for radiated disturbance	
	measurements using a TEM waveguide	81
F.4	Figures for Annex F	87
Annex G (	informative) Measurement uncertainty of immunity testing due to test	
instrumen	tation	89
G.1	General symbols	89
G.2	Symbol and definition of the measurand	89
G.3	Symbols for input quantities	89
G.4	Example: Uncertainty budget for immunity test	89
G.5	Rationale for the estimates of input quantities	90
Annex H (	informative) Correlation of emission and immunity limits between EMC test	
facilities	· · · · · · · · · · · · · · · · · · ·	93
H.1	Overview	93
H.2	Dipole in free space (representing FAR set-up)	93
H.3	Dipole in half space (representing OATS or SAC set-up)	95
H.4	Dipole in a TEM-mode transmission line	96
H.5	Dipole in a reverberation chamber	97
H.6	, Correlation	98
H.7	Example of emission limits	
H.8	Figures for Annex H	100
Annex I (ii	nformative) TEM waveguide transient characterization	103
1		102
1.1		103

#### IEC 61000-4-20:2022 © IEC 2022 - 5 -

1.2	Test equipment	103
1.3	Test set-up	103
1.4	TEM waveguide characterization by correlation	104
I.5	Quantification of the Pcc	105
I.6	Performable transient test signals	105
1.7	Figures for Annex I	106
Bibliograp	ɔhy	

Figure 1 – Flowchart of TEM mode and field uniformity verification procedure with the "constant forward power" method (see 5.2.2.4.1)	24
Figure 2 – Flowchart of TEM mode and field uniformity verification procedure with the "constant field strength" method (see 5.2.2.4.2)	25
Figure A.1 – Routing the exit cable to the corner at the ortho-angle and the lower edge of the test volume in a TEM waveguide (see A.5.2)	39
Figure A.2 – Basic ortho-axis EUT positioner or manipulator (see 3.1.13, A.4.2, A.5.1.2, A.5.2)	40
Figure A.3 – Die pattern and axis alignment for an EUT [26] (see A.3.2.3.2)	41
Figure A.4 – Non-redundant twelve-face and axis orientations for a typical EUT [26] (see A.3.2.3.2)	42
Figure A.5 – Open-area test site (OATS) emission measurements geometry (see A.3.2.4)	43
Figure B.1 – Example of test set-up for single-polarization TEM waveguide (see Clause B.5)	47
Figure B.2 – Uniform area calibration points in a TEM waveguide (see Clause B.3)	48
Figure C.1 – Pulse waveform frequency domain spectral magnitude between 100 kHz and 300 MHz (see C.2.1)	55
Figure D.1 – Simple waveguide (no TEM mode) (see D.3.3)	61
Figure D.2 – Example of waveguides supporting TEM-mode propagation (see D.3.3)	61
Figure D.3 – E-field polarization vector (see Clause D.5)	61
Figure D.4 – Simple transmission line model for TEM mode propagation (see D.6.1)	62
Figure D.5 – One- and two-port TEM waveguide concepts (see D.6.1)	62
Figure D.6 – Operation of four-port TEM waveguides (see D.6.1)	62
Figure D.7 – Two-port TEM cell (symmetric septum) (see D.6.1 and D.6.3)	63
Figure D.8 – One-port TEM cell (asymmetric septum) (see D.6.1 and D.6.3)	64
Figure D.9 – Stripline (two plates) (see D.6.1 and D.6.2)	66
Figure D.10 – Stripline (four plates, balanced feed) (see D.6.1)	67
Figure D.11 – Four-port TEM waveguide (symmetric parallel septa) (see D.6.1 and D.6.3)	68
Figure E.1 – Example of test points for calibration volume validation (see E.2.3)	77
Figure E.2 – Set-up for validation of probe perturbation (see E.2.5)	77
Figure E.3 – Set-up for measuring net power to a transmitting device (not to scale) (see E.3.4)	77
Figure E.4 – Example set-up for E-field probe calibration with two-port TEM waveguide (see E.4.2)	78
Figure E.5 – Example set-up for E-field probe calibration with one-port TEM waveguide and alternative method (see E.4.3.2)	78
Figure E.6 – Equivalent circuit of monopole antenna and measuring apparatus (see E.4.3.3)	78

#### – 6 – IEC 61000-4-20:2022 © IEC 2022

Figure F.1 – Deviation of the QP detector level indication from the signal level at receiver input for two cases, a sine-wave signal and an impulsive signal with a pulse repetition frequency of 100 Hz	87
Figure F.2 – Deviation of the peak detector level indication from the signal level at receiver input for two cases, a sine-wave signal and an impulsive signal with a pulse repetition frequency of 100 Hz	88
Figure H.1 – Representation of a short centre-fed dipole and a more general source representing an EUT (see Clause H.2)	100
Figure H.2 – Vertical source and receiving dipoles located over a perfectly-conducting ground plane of infinite extent (see Clause H.3)	100
Figure H.3 – Two types of TEM cells with a vertically polarized dipole source and the source to receive port geometry defined (see Clause H.4)	101
Figure H.4 – Reverberation chamber with a source dipole, a stirrer to randomize the fields, and a general receive antenna (see Clause H.5)	101
Figure H.5 – TEM waveguide Class A and Class B emission limits correlated from CISPR 32 [68] (see Clause H.7)	102
Figure I.1 – Test set-up	106
Figure I.2 – Signal windowing	107
Figure I.3 – Example of a heatmap – Pcc for a test point in the uniform area	107
Table 1 – Values k for expanded uncertainty with normal distribution	18
Table B.1 – Uniform area calibration points	45
Table B.2 – Test levels	45
Table C.1 – Radiated immunity test levels defined for this document	50
Table E.1 – Calibration frequencies	71
Table E.2 – Calibration field strength level	71
Table F.1 – Uncertainty budget for radiated disturbance measurement results using a TEM waveguide from 30 MHz to 1 000 MHz (example)	80
Table F.2 – Uncertainty budget for radiated disturbance measurement results using aTEM waveguide from 1 GHz to 6 GHz (example)	81
Table F.3 – Values of <i>S</i> lim for 30 MHz to 1 000 MHz	83
Table F.4 – Values of <i>S</i> lim for 1 GHz to 6 GHz	84
Table G.1 – Example uncertainty budget of the immunity test level	90
Table H.1 – Summary of the emission correlation parameters	99

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- 7 -

#### INTERNATIONAL ELECTROTECHNICAL COMMISSION

#### ELECTROMAGNETIC COMPATIBILITY (EMC) -

#### Part 4-20: Testing and measurement techniques – Emission and immunity testing in transverse electromagnetic (TEM) waveguides

#### FOREWORD

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International Standard IEC 61000-4-20 has been prepared by subcommittee 77B: High frequency phenomena, of IEC technical committee 77: Electromagnetic compatibility, in cooperation with CISPR (International Special Committee on Radio Interference) subcommittee A: Radio-interference measurements and statistical methods.

It forms Part 4-20 of IEC 61000. It has the status of a basic EMC publication in accordance with IEC Guide 107.

This third edition cancels and replaces the second edition published in 2010. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

a) provide information on the testing of large EUTs (including cables);

- b) apply the work on measurement uncertainties by adapting the work completed in CISPR and TC 77 (for emissions and immunity);
- c) update the validation procedure for the test volume regarding field uniformity and TEM mode verification;
- d) provide information concerning two-port and four-port TEM waveguides;
- e) add a new informative annex (Annex I) dealing with transient TEM waveguide characterization; and
- f) add information dealing with dielectric test stands for EUTs.

The text of this International Standard is based on the following documents:

Draft	Report on voting
77B/853/FDIS	77B/855/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members\_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/standardsdev/publications.

A list of all parts of the IEC 61000 series, published under the general title *Electromagnetic compatibility (EMC)*, can be found on the IEC website.

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The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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-9-

#### INTRODUCTION

IEC 61000 is published in separate parts according to the following structure:

#### Part 1: General

General considerations (introduction, fundamental principles) Definitions, terminology

#### Part 2: Environment

Description of the environment

Classification of the environment

Compatibility levels

#### Part 3: Limits

**Emission limits** 

Immunity limits (in so far as they do not fall under the responsibility of the product committees)

#### Part 4: Testing and measurement techniques

Measurement techniques		
Testing techniques		

### Part 5: Installation and mitigation guidelines

Installation guidelines

SIST EN IEC 61000-4-20:2022

Mitigation methods and devices atalog/standards/sist/37eddb27-726f-43fd-89c2-

### Part 6: Generic standards<sup>05c1036930/sist-en-iec-61000-4-20-2022</sup>

#### Part 9: Miscellaneous

Each part is further subdivided into several parts, published either as International Standards, Technical Specifications or Technical Reports, some of which have already been published as sections. Others are and will be published with the part number followed by a dash and a second number identifying the subdivision (example: IEC 61000-6-1).

This part is an International Standard which gives emission, immunity and HEMP and IEMI transient testing requirements.